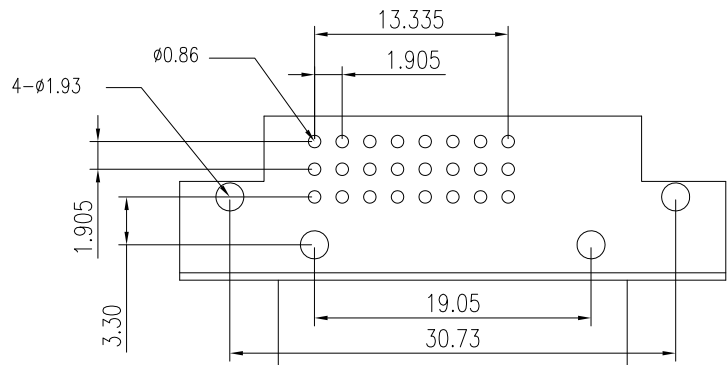
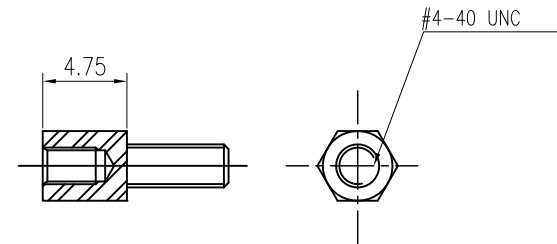
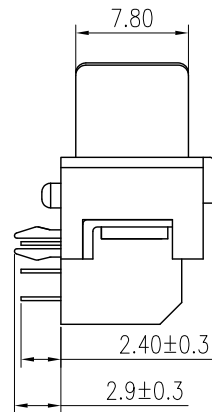
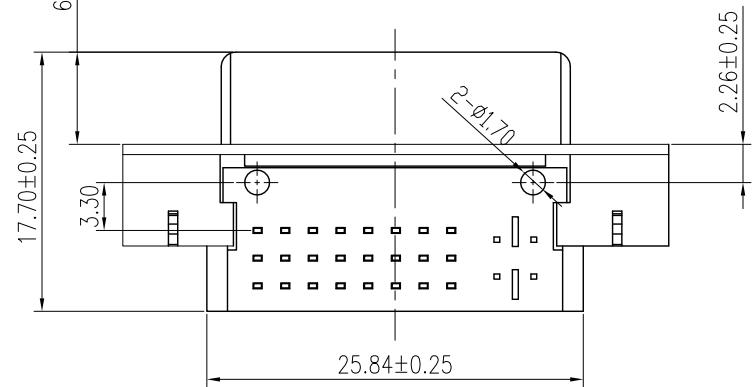
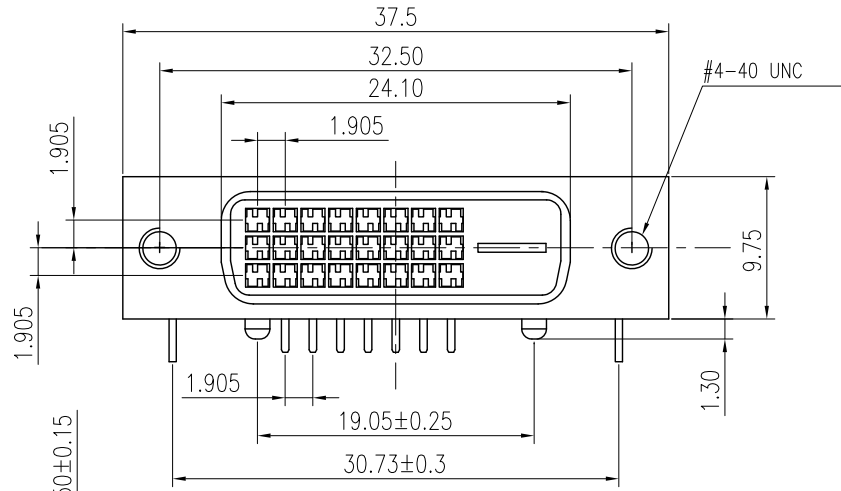


RoHS

GP

HF

REV.	ECR/N NO.	DESCRIPTION	DRAWN	DATE
A	/	NEW	DENGJU	2017/05/24



P.C.B LAYOUT(TOP VIEW)

NOTE:

BODY: PBT+30%GF  
 SPACER: PA66+30%GF  
 CONTACTS: COPPER ALLOY  
 CONTACT : COPPER ALLOY  
 CONTACT : UNDER PLATED 50u"MIN NICKEL,  
 OVER ALL 120u" MIN TIN IN SOLDERING AREA,  
 SELECTIVE GOLD PLATED IN CONTACT AREA.  
 SHIELD : SPCC T=0.5  
 SHIELD : NICKEL PLATED WITH 120u"THICK.  
 OVER 100u" THICKNESS Cu.  
 BOARD LOCK:SPCC ,Tin PLATED.  
 RIVET : COPPER ALLOY , NICKEL PLATED.  
 SCREW : Fe,NICKEL PLATED.

\*MECHANICAL

MATING FORCE: 4.5 KG MAX. 25 MM/MINUTE  
 UNMATING FORCE: 1.0-4.0 KG MIN.  
 DURABILITY: 100 MATING CYCLES

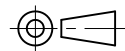
\*ELECTRICAL SPECIFICATION

INSULATION RESISTANCE: 1000 MEGOHMS MIN  
 DIELECTRIC WITHSTANDING VOLTAGE: 500V AC RMS±50V.60 HZ  
 CURRENT RATING: 1.5 AMPERES MIN

\*ENVIRONMENTAL

OPERATING TEMPERATURE: -20°C to 85°C

TOLERANCE	MODEL NAME: DVI24+1(24+1胶芯)柳附锁4.75 短柱	DRAWN:	DENGJU
X.X ±0.35	MODEL NO: WLDV-090A	CHECKED:	WUXIAOTAO
X.XX ±0.25	UNIT:	APPROVED:	WUHUAMING
X.XXX ±0.10	SCALE: 1:1	DATE:	2017/05/24
ANGLE ±1.0°	REVISION: A	DWG NO:	
	SHEET 1/1	FILE:	C



**WLCO** 深圳市兴万联电子有限公司  
 SHENZHEN XING WAN LIAN ELECTRONICS CO., LTD.